

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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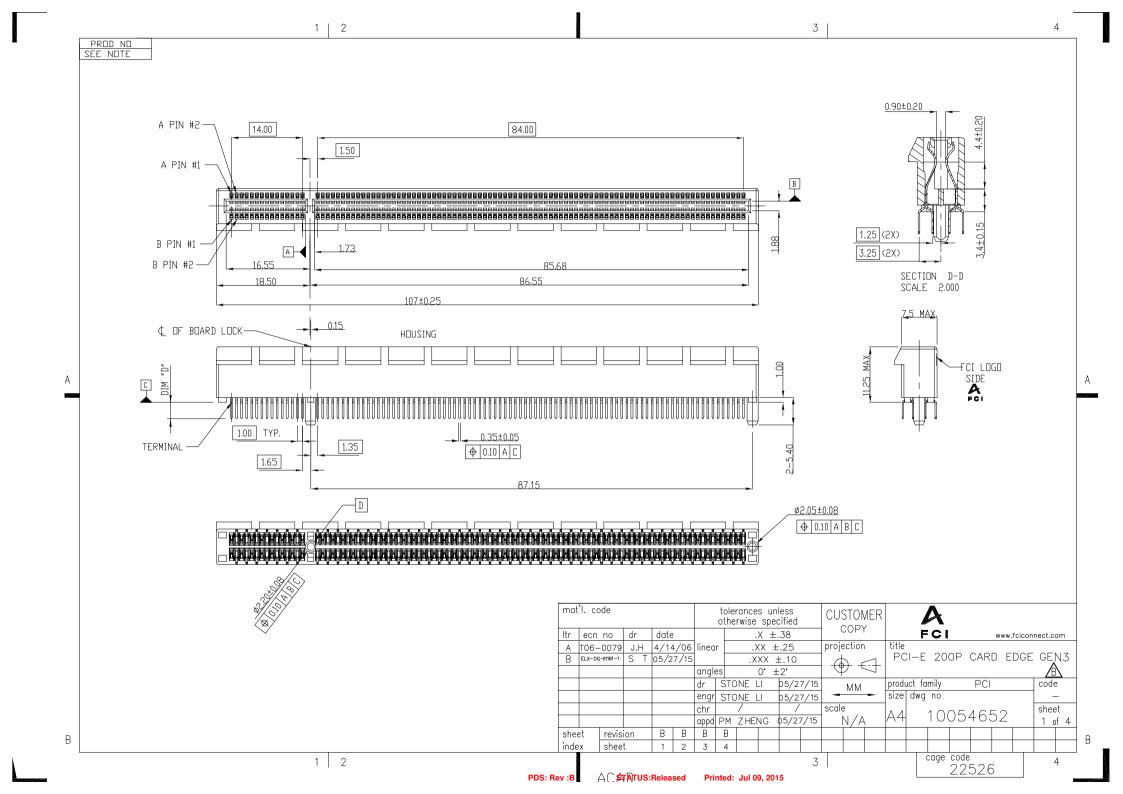
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

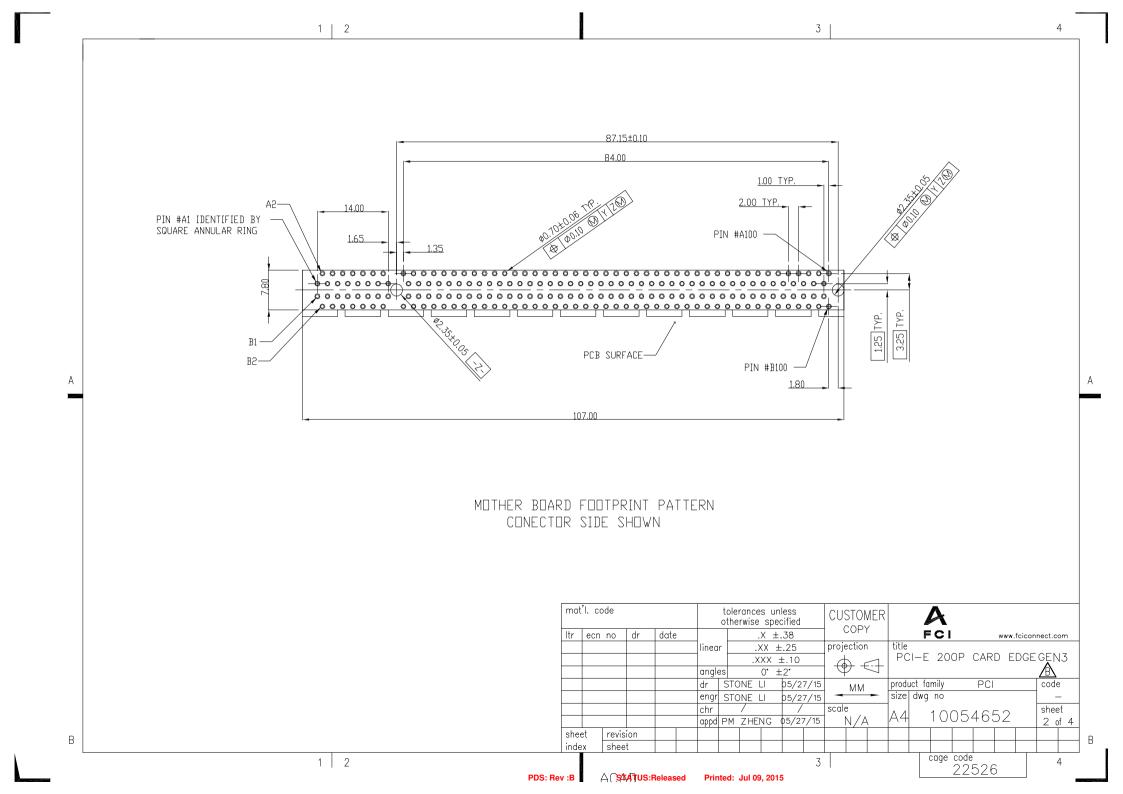
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

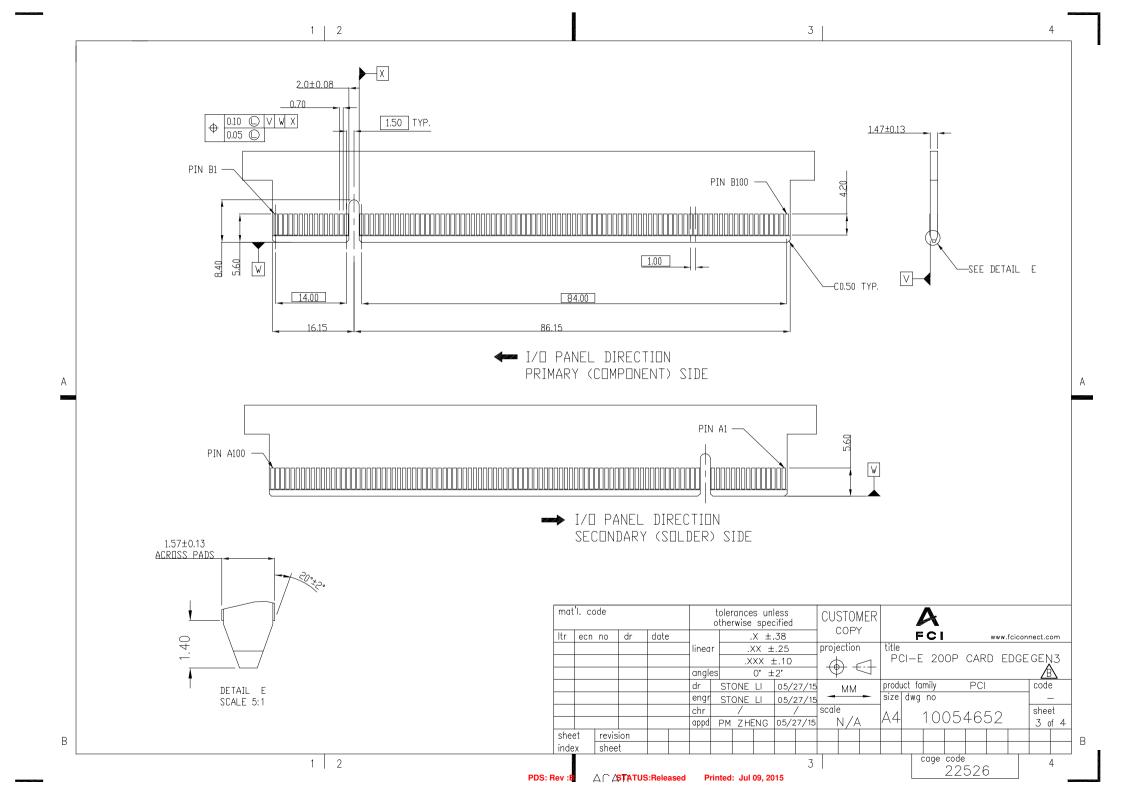












3 1 NOTES: 1.MATERIAL: HOUSING: THERMOPLASTIC WITH GLASS FIBER, UL94V-0, COLOR IN BLACK. CONTACTS: COPPER ALLOY. 2.FINISH: CONTACTS: GOLD PLATING ON CONTACT AREA, 100 u"MIN, TIN/LEAD OR MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDERTAILS, 50u"MIN. NICKEL UNDERPLATING OVER ALL. BNARDLINCKS: 100 4" TIN/LEAD OR MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDERTAILS. 504"MIN, NICKEL UNDERPLATING OVER ALL. 3. DURABILITY: 50 CYCLES. 4. RoHS COMPATIBLE PRODUCT SPECIFICATIONS a, PLATING: "LF" MEANS THE PRODUCT IS LEAD FREE, 2.5um min. MATTE PURE TIN OVER 1.27um MIN. NICKEL UNDERPLATE. b. MANUFACTURING PROCESS COMPATIBILITY: THE HOUSING WILL WITHSTAND EXPOSURE TO 2600°±50° SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60MM THICK CIRCUIT BOARD. PRODUCT NUMBER CODE 10054652 - X X X X X X LF - FAD FRFF HOUSING COLOR OPTIONS PACKAGING OPTIONS T-TRAY PACKAGING RESERVE 0 TERMINAL PLATING OPTIONS TAIL LENGTH OPTIONS 0-50u" Ni UNDERPLATE DIM "D" 30u" Au CONTACT AREA SUGGESTED PCB THICKNESS 100u" TIN TAIL AREA -----COMPATIBLE ROHS 1 3.10 2.36±0.10 1-50u" Ni UNDERPLATE 2 2.54 1.56±0.10 15u" Au CONTACT AREA 100u" TIN TAIL AREA ------COMPATIBLE ROHS 2-50u" Ni UNDERPLATE GOLD FLASH CONTACT AREA 100u" TIN TAIL AREA -----COMPATIBLE ROHS mat'l. code tolerances unless CUSTOMER otherwise specified COPY FCI Itr ecn no dr date .X ±.38 www.fciconnect.com projection .XX ±.25 linear PCI-E 200P CARD EDGEGEN3 .XXX ±.10  $\oplus$ angles 0° ±2° dr STONE LI 05/27/15 product family PCI code MM size dwg no engr STONE LI 05/27/15 chr scale sheet 10054652 appd PM ZHENG 05/27/15 N/A 4 of 4

В

1-BLACK

PEGS OPTIONS

0-PLASTIC PEGS

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PDS: Rev :B

sheet

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∧ C STATUS:Released Printed: Jul 09, 2015

revision

sheet

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cage code 22526